

# PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Kenji Mitomo	08/21/2011
Kenji Oka	08/21/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HITACHI HIGH-TECHNOLOGIES CORPORATION
<b>Street Address:</b>	24-14, Nishi Shinbashi 1-chome, Minato-ku
<b>City:</b>	Tokyo
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	105-8717
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13202727
<b>CORRESPONDENCE DATA</b>	
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<b>Correspondent Name:</b>	MCDERMOTT WILL & EMERY LLP
<b>Address Line 1:</b>	600 13TH STREET, N.W.
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<b>ATTORNEY DOCKET NUMBER:</b>	081183-0016
<b>NAME OF SUBMITTER:</b>	Keith E. George 34,111 jcm
<b>Total Attachments: 2</b> source=2011-11-02_Assi_081183-0016#page1.tif source=2011-11-02_Assi_081183-0016#page2.tif	

CH \$40.00 13202727

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**PATENT**  
**REEL: 027164 FRAME: 0091**

RECORDATION FORM COVER SHEET

**Docket No.: 081183-0016**

**PATENTS ONLY**

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

**1. Name of Conveying Party(ies)**

**Kenji MITOMO; Kenji OKA**

Additional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

**3. Nature of Conveyance/Execution Date(s)**

Execution Date(s): **August 21, 2011**

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Joint Research Agreement  
☐ Government Interest Assignment  
☐ Executive Order 9424, Confirmatory License  
☐ Other

**2. Name and address of receiving party(ies)**

Name: **HITACHI HIGH-TECHNOLOGIES CORPORATION**

Internal Address:

Address: **24-14, Nishi Shinbashi 1-chome,  
Minato-ku, Tokyo,  
JAPAN 105-8717**

Additional name(s) & address(es) attached? ☐ Yes ☐ No

**4. Application or patent number(s):**

A. Patent Application No(s).

**13/202,727**

☐ This document is being filed together with a new application.

B. Patent No(s).

Additional numbers attached? ☐ Yes ☐ No

**5. Name and address to whom correspondence concerning document should be mailed:**

Name: **MCDERMOTT WILL & EMERY LLP**

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D.C.

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**6. Total number of applications and patents involved: 1**

**7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00**

- ☐ Authorized to be charged by credit card  
☒ Authorized to be charged to deposit account  
☐ Enclosed  
☐ None required (government interest not affecting title)

**8. Payment Information:**

- a. Credit Card Last 4 Numbers \_\_\_\_\_  
Expiration Date \_\_\_\_\_  
b. Deposit Account Number **500417**  
Authorized User Name \_\_\_\_\_

**9. Signature.**

**Keith E. George 34,111**

**November 2, 2011**

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments and documents:

**2**

## ASSIGNMENT

( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI HIGH-TECHNOLOGIES CORPORATION, a corporation organized under the laws of Japan, located at 24-14, Nishi Shinbashi 1-chome, Minato-ku, Tokyo, 105-8717 Japan, receipt of which is hereby acknowledged, I do hereby sell and assign to said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

### INSPECTION METHOD AND INSPECTION APPARATUS

Invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI HIGH-TECHNOLOGIES CORPORATION.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1)	<u>Kenji Mitomo</u> Kenji MITOMO	<u>8/21/2011</u>
2)	<u>Kenji Oka</u> Kenji OKA	<u>8/21/2011</u>
3)	_____	_____
4)	_____	_____
5)	_____	_____